
N-Channel Enhancement-Mode Vertical DMOS FET

Features

- Free from Secondary Breakdown
- Low Power Drive Requirement
- Ease of Paralleling
- Low C_{ISS} and Fast Switching Speeds
- Excellent Thermal Stability
- Integral Source-Drain Diode
- High Input Impedance and High Gain

Applications

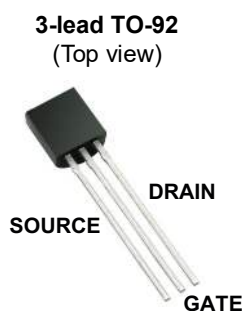
- Motor Controls
- Converters
- Amplifiers
- Switches
- Power Supply Circuits
- Drivers (Relays, Hammers, Solenoids, Lamps, Memories, Displays, Bipolar Transistors, etc.)

General Description

The VN10K Enhancement-mode (normally-off) transistors uses a vertical DMOS structure and a well-proven silicon-gate manufacturing process. This combination produces a device with the power handling capabilities of bipolar transistors and the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, this device is free from thermal runaway and thermally induced secondary breakdown.

Microchip's vertical DMOS FETs are ideally suited for a wide range of switching and amplifying applications where very low threshold voltage, high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

Package Type



See [Table 3-1](#) for pin information.

VN10K

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings†

Drain-to-Source Voltage	BV_{DSS}
Drain-to-Gate Voltage	BV_{DGS}
Gate-to-Source Voltage	$\pm 30V$
Operating Ambient Temperature, T_A	$-55^{\circ}C$ to $+150^{\circ}C$
Storage Temperature, T_S	$-55^{\circ}C$ to $+150^{\circ}C$

† **Notice:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

Electrical Specifications: $T_A = 25^{\circ}C$ unless otherwise specified. All DC parameters are 100% tested at $25^{\circ}C$ unless otherwise stated. Pulse test: 300 μs pulse, 2% duty cycle

Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
Drain-to-Source Breakdown Voltage	BV_{DSS}	60	—	—	V	$V_{GS} = 0V, I_D = 100 \mu A$
Gate Threshold Voltage	$V_{GS(th)}$	0.8	—	2.5	V	$V_{GS} = V_{DS}, I_D = 1 mA$
Change in $V_{GS(th)}$ with Temperature	$\Delta V_{GS(th)}$	—	-3.8	—	mV/ $^{\circ}C$	$V_{GS} = V_{DS}, I_D = 1 mA$ (Note 1)
Gate Body Leakage Current	I_{GSS}	—	—	100	nA	$V_{GS} = 15V, V_{DS} = 0V$
Zero-Gate Voltage Drain Current	I_{DSS}	—	—	10	μA	$V_{GS} = 0V, V_{DS} = 45V$
		—	—	500	μA	$V_{GS} = 0V, V_{DS} = 45V,$ $T_A = 125^{\circ}C$ (Note 1)
On-State Drain Current	$I_{D(ON)}$	0.75	—	—	A	$V_{GS} = 10V, V_{DS} = 10V$
Static Drain-to-Source On-State Resistance	$R_{DS(ON)}$	—	—	7.5	Ω	$V_{GS} = 5V, I_D = 200 mA$
		—	—	5	Ω	$V_{GS} = 10V, I_D = 500 mA$
Change in $R_{DS(ON)}$ with Temperature	$\Delta R_{DS(ON)}$	—	0.7	—	%/ $^{\circ}C$	$V_{GS} = 10V, I_D = 500 mA$ (Note 1)

Note 1: Specification is obtained by characterization and is not 100% tested.

AC ELECTRICAL CHARACTERISTICS

Electrical Specifications: $T_A = 25^\circ\text{C}$ unless otherwise specified. All AC parameters are not 100% sample tested.

Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
Forward Transconductance	G_{FS}	100	—	—	mmho	$V_{DS} = 10\text{V}$, $I_D = 500\text{ mA}$
Input Capacitance	C_{ISS}	—	48	60	pF	$V_{GS} = 0\text{V}$, $V_{DS} = 25\text{V}$, $f = 1\text{ MHz}$
Common-Source Output Capacitance	C_{OSS}	—	16	25	pF	
Reverse Transfer Capacitance	C_{RSS}	—	2	5	pF	
Turn-On Time	$t_{(ON)}$	—	—	10	ns	$V_{DD} = 15\text{V}$, $I_D = 600\text{ mA}$, $R_{GEN} = 25\Omega$
Turn-Off Time	$t_{(OFF)}$	—	—	10	ns	
DIODE PARAMETER						
Diode Forward Voltage Drop	V_{SD}	—	0.8	—	V	$V_{GS} = 0\text{V}$, $I_{SD} = 500\text{ mA}$ (Note 1)
Reverse Recovery Time	t_{rr}	—	160	—	ns	$V_{GS} = 0\text{V}$, $I_{SD} = 500\text{ mA}$

Note 1: Unless otherwise stated, all DC parameters are 100% tested at 25°C . Pulse test: 300 μs pulse, 2% duty cycle

TEMPERATURE SPECIFICATIONS

Parameter	Sym.	Min.	Typ.	Max.	Unit	Conditions
TEMPERATURE RANGE						
Operating Ambient Temperature	T_A	-55	—	+150	$^\circ\text{C}$	
Storage Temperature	T_S	-55	—	+150	$^\circ\text{C}$	
PACKAGE THERMAL RESISTANCE						
3-lead TO-92	θ_{JA}	—	132	—	$^\circ\text{C/W}$	

THERMAL CHARACTERISTICS

Package	I_D (Note 1) (Continuous) (mA)	I_D (Pulsed) (A)	Power Dissipation at $T_A = 25^\circ\text{C}$ (W)	I_{DR} (Note 1) (mA)	I_{DRM} (A)
3-lead TO-92	310	1	1	310	1

Note 1: I_D (continuous) is limited by maximum rated T_J .

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g. outside specified power supply range) and therefore outside the warranted range.

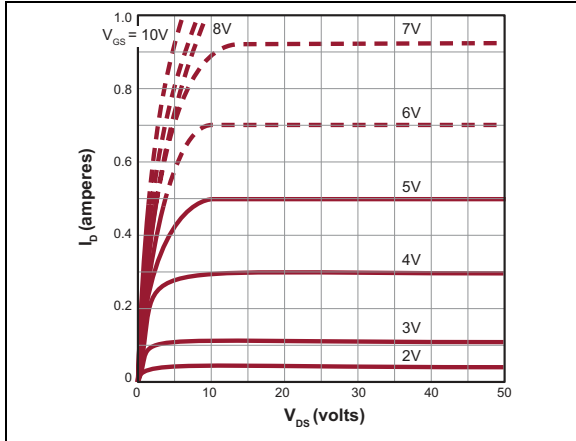


FIGURE 2-1: Output Characteristics.

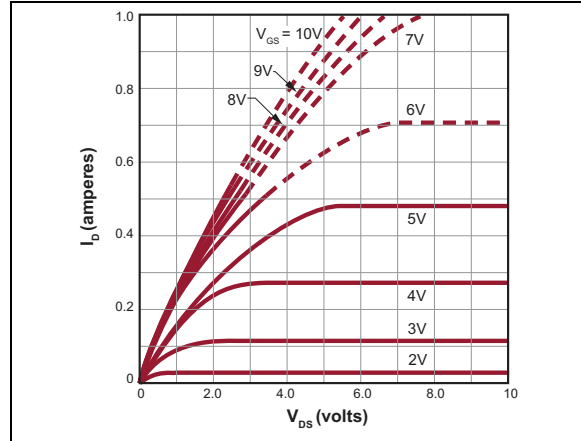


FIGURE 2-4: Saturation Characteristics.

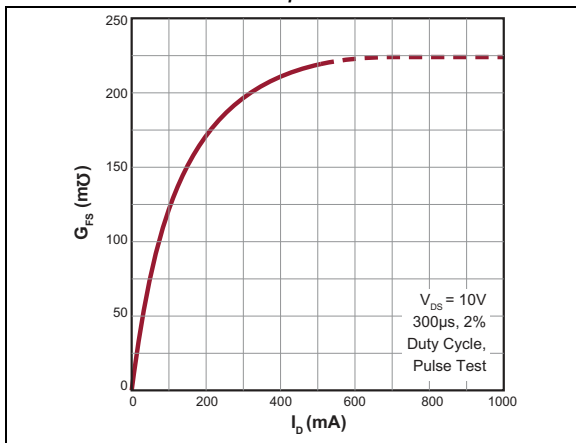


FIGURE 2-2: Transconductance vs. Drain Current.

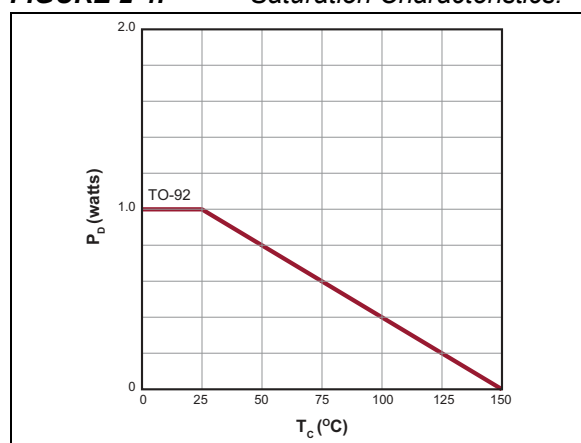


FIGURE 2-5: Power Dissipation vs. Case Temperature.

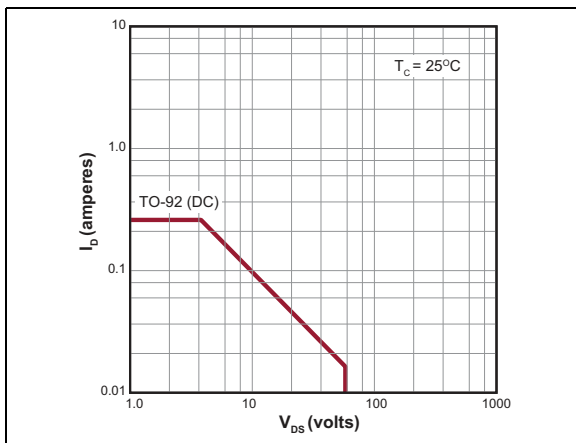


FIGURE 2-3: Maximum Rated Safe Operating Area.

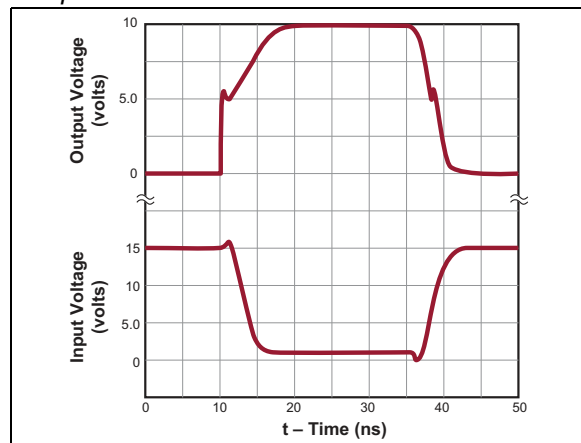


FIGURE 2-6: Switching Waveform.

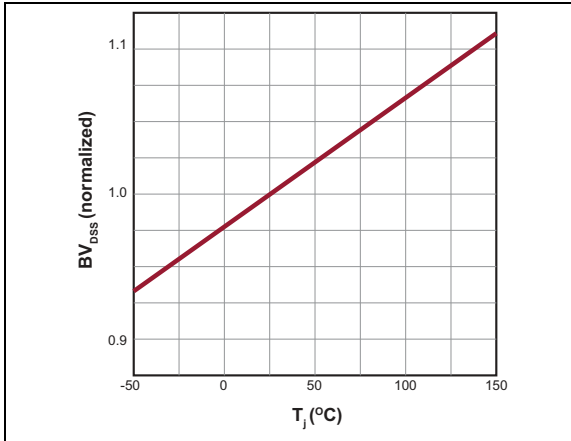


FIGURE 2-7: BV_{DSS} Variation with Temperature.

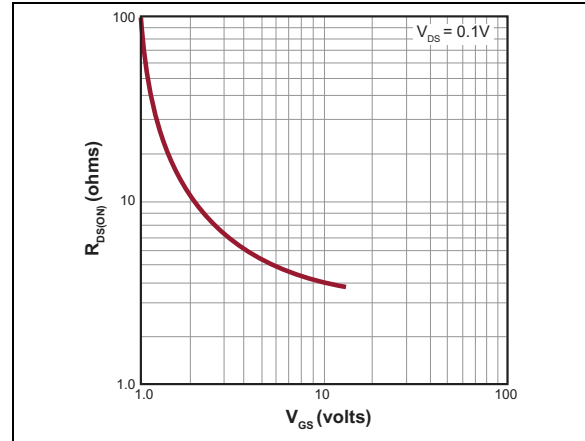


FIGURE 2-10: On-Resistance vs. Gate-to-Source Current.

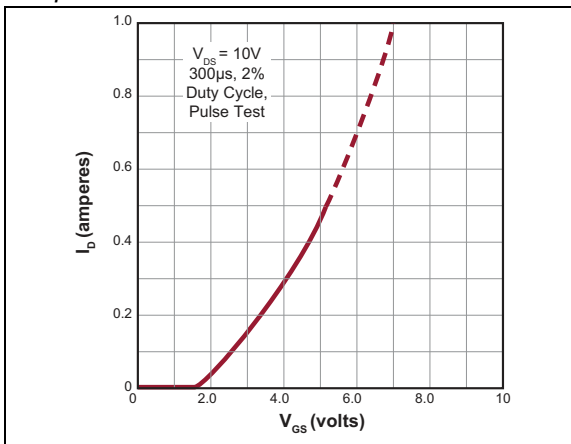


FIGURE 2-8: Transfer Characteristics.

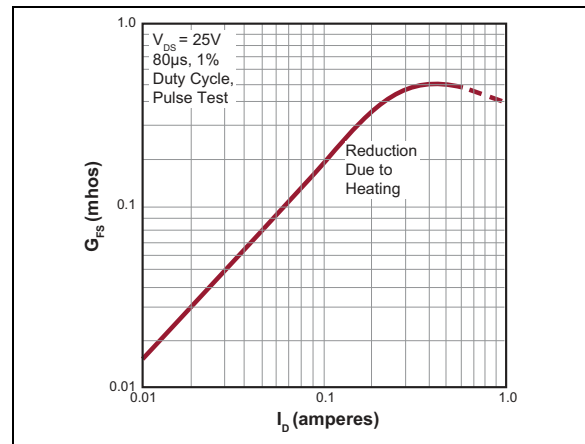


FIGURE 2-11: Output Conductance vs. Drain Current.

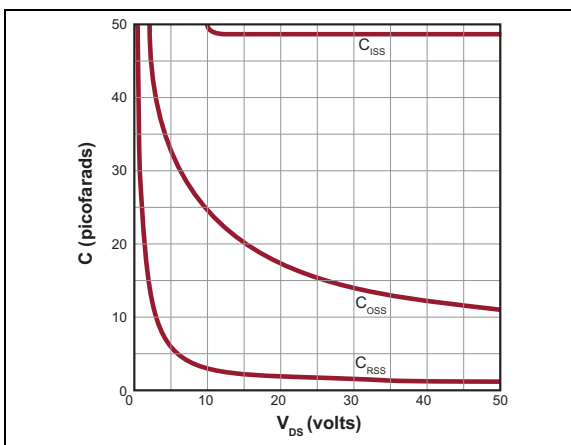


FIGURE 2-9: Capacitance vs. Drain-to-Source Voltage.

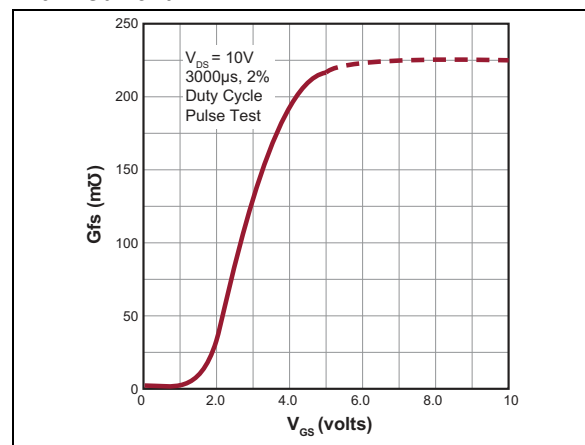


FIGURE 2-12: Transconductance vs. Gate-to-Source Voltage.

VN10K

3.0 PIN DESCRIPTION

The details on the pins of VN10K are listed in [Table 3-1](#). Refer to [Package Type](#) for the location of the pins.

TABLE 3-1: PIN FUNCTION TABLE

Pin Number	Pin Name	Description
1	Source	Source
2	Gate	Gate
3	Drain	Drain

4.0 FUNCTIONAL DESCRIPTION

Figure 4-1 illustrates the switching waveforms and test circuit for VN10K.

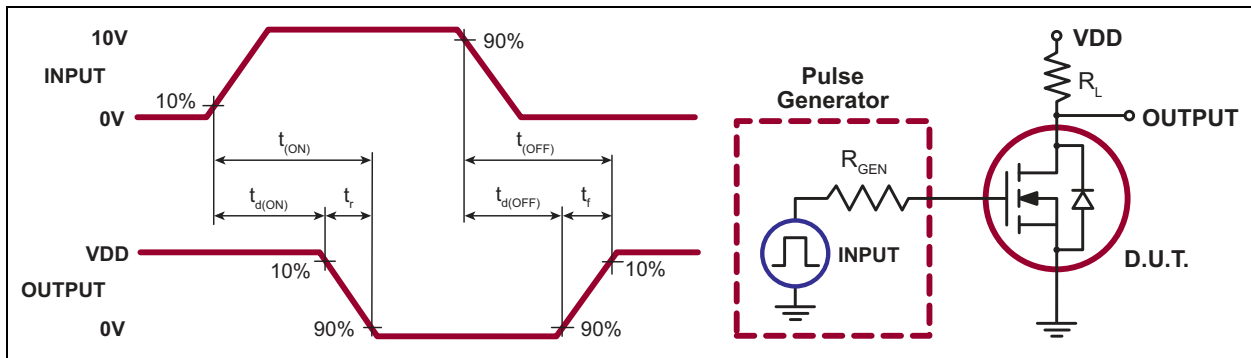


FIGURE 4-1: Switching Waveforms and Test Circuit.

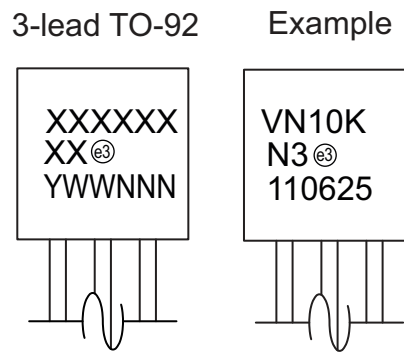
TABLE 4-1: PRODUCT SUMMARY

BV_{DSS}/BV_{DGS} (V)	$R_{DS(ON)}$ (Maximum) (Ω)	I_{DSS} (Minimum) (mA)
60	5	750

VN10K

5.0 PACKAGING INFORMATION

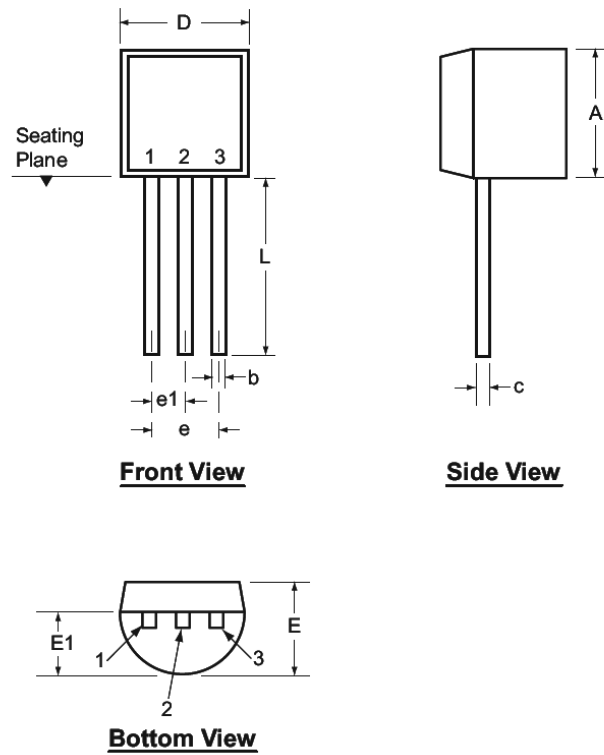
5.1 Package Marking Information



Legend:	XX...X	Product Code or Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for product code or customer-specific information. Package may or not include the corporate logo.

3-Lead TO-92 Package Outline (L/LL/N3)



Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

Symbol		A	b	c	D	E	E1	e	e1	L
Dimensions (inches)	MIN	.170	.014 [†]	.014 [†]	.175	.125	.080	.095	.045	.500
	NOM	-	-	-	-	-	-	-	-	-
	MAX	.210	.022 [†]	.022 [†]	.205	.165	.105	.105	.055	.610*

JEDEC Registration TO-92.

* This dimension is not specified in the JEDEC drawing.

† This dimension differs from the JEDEC drawing.

Drawings not to scale.

VN10K

NOTES:

APPENDIX A: REVISION HISTORY

Revision A (July 2021)

- Converted Supertex Doc# DSFP-VN10K to Microchip DS20005983A
- Added a pin function table
- Changed the package marking format
- Removed the 3-lead TO-92 N3 P005 media type to align packaging specifications with the actual BQM
- Made minor text changes throughout the document

VN10K

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

<u>PART NO.</u>					
Device	XX Package Options	-	X Environmental	-	X Media Type
Device:	VN10K	=	N-Channel Enhancement-Mode Vertical DMOS FET		
Package:	N3	=	3-lead TO-92		
Environmental:	G	=	Lead (Pb)-free/RoHS-compliant Package		
Media Types:	(blank)	=	1000/Bag for an N3 Package		
	P002	=	2000/Reel (Reverse T/R) for an N3 Package		
	P003	=	2000/Reel for an N3 Package		
	P013	=	2000/AMMO Pack for an N3 Package		
	P014	=	2000/AMMO Pack for an N3 Package		

Examples:	
a) VN10KN3-G:	N-Channel Enhancement-Mode, Vertical DMOS FET, 3-lead TO-92, 1000/Bag
b) VN10KN3-G-P003:	N-Channel Enhancement-Mode, Vertical DMOS FET, 3-lead TO-92, 2000/Reel (Reverse T/R)
c) VN10KN3-G-P013:	N-Channel Enhancement-Mode, Vertical DMOS FET, 3-lead TO-92, 2000/AMMO Pack

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